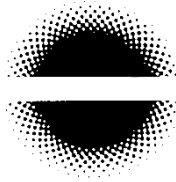


Second Announcement and Call for Papers



ICRP-11/GEC 2022

**October 3 - 7, 2022
Sendai International Center
Sendai, Japan**

**11th International Conference on Reactive Plasmas /
75th Annual Gaseous Electronics Conference /
40th Symposium on Plasma Processing (SPP-40) /
35th Symposium on Plasma Science for Materials (SPSM35)**



Organized by

International Organizing Committee of ICRP-11

GEC Executive Committee

Co-sponsored by

The Japan Society of Applied Physics

Supported by:

American Physical Society

Plasma Electronics Division, The Japan Society of Applied Physics

<https://www.ecei.tohoku.ac.jp/plasma/ICRP-11/>

Cooperative Societies

Japan Welding Society
Smart Processing Society for Materials, Environment & Energy
The Chemical Society of Japan
The Electrochemical Society of Japan
The Institute of Electrical Engineers of Japan
The Institute of Electronics, Information and Communication Engineers
The Institute of Electrostatics Japan
The Institute of Engineers on Electrical Discharges in Japan
The Japan Society of Mechanical Engineers
The Japan Society of Plasma Science and Nuclear Fusion Research
The Japan Society of Vacuum and Surface Science
The Materials Research Society of Japan
The Physical Society of Japan
The Society of Chemical Engineers, Japan
The Surface Finishing Society of Japan

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General Information

The International Conference on Reactive Plasmas (ICRP) has taken place by the initiative of the Division of Plasma Electronics, the Japan Society of Applied Physics since 1991. The 1st ICRP was held in Nagoya, the 2nd in Yokohama (1994), the 3rd in Nara (1997), and the most recent conference (10th ICRP) in Sapporo (2019). Some former ICRPs were held as international joint conferences: the 4th ICRP was with the Gaseous Electronics Conference (GEC) at Maui in 1998, the 5th was with European Conference on the Atomic and Molecular Physics of Ionized Gases (ESCAMPIG) at Grenoble (2002), the 7th was with GEC at Paris in 2010, 9th was with GEC at Honolulu in 2015, and 10th was with International Conference on Phenomena in Ionized Gases (ICPIG) at Sapporo in 2019. The Symposium on Plasma Processing (SPP) is a domestic annual Japanese meeting that has been held by the Division of Plasma Electronics since 1984. The joint ICRP and SPP conference aims to gather researchers and engineers, involved in various aspects of reactive plasmas and their applications. The joint conference also aims to facilitate the exchange of information and ideas among them within an international framework.

The subjects covered in this conference are the entire field of reactive plasmas and their applications to various materials processing such as surface modification, etching and deposition with emphasis on basic phenomena, technologies, and the underlying basic physics and chemistry. Furthermore, the subjects have been extended to bio- and/or medical application of plasmas. This conference particularly encourages papers dealing with basic properties of the plasma itself, its generation and control, fundamental processes in the plasma, and plasma-solid/liquid interactions. Papers dealing with specific results of processing should place emphasis on the related plasma characteristics in obtaining the results.

The 11th ICRP will take place in October 3-7, 2022, in Sendai, Japan, as a joint conference with the 75th GEC. This conference will also be held as a joint conference with the 40th Symposium on Plasma Processing and 35th Symposium on Plasma Science for Materials (SPSM35). The conference site will be at Sendai International Center at Sendai.

The ICRP-11/GEC2022/SPP-40/SPSM35, a four-day conference, will consist of a series of oral sessions (composed of both invited and contributed papers), poster sessions, award lectures, and arranged sessions on selected topics. Sessions will be organized around coherent subjects in order to facilitate useful discussions and focus on appropriate solutions to problems.

The official language of the conference is English, and will be used for all presentations and printed materials.



Scientific Program

Conference Topics

General Sessions:

1 Atomic and molecular collisional and dynamical processes

- 1.1 Electron and photon collisions with atoms and molecules: excitation
- 1.2 Electron and photon collisions with atoms and molecules: ionization
- 1.3 Heavy-particle collisions
- 1.4 Dissociation, recombination and attachment
- 1.5 Distribution functions and transport coefficients for electrons and ions
- 1.6 Other atomic and molecular collision phenomena

2 Plasma science

- 2.1 Nonequilibrium kinetics of low-temperature plasmas
- 2.2 Basic plasma physics phenomena in low-temperature plasmas
- 2.3 Plasma boundaries: sheaths, boundary layers, others
- 2.4 Plasma-surface interactions
- 2.5 Plasma diagnostic techniques
- 2.6 Modeling and simulation: computational methods
- 2.7 Modeling and simulation: validation and verification
- 2.8 Modeling and simulation: plasma sources
- 2.9 Modeling and simulation: chemical reactions
- 2.10 Modeling and simulation: other
- 2.11 Glows: dc, pulsed, microwave, others
- 2.12 Capacitively coupled plasmas
- 2.13 Inductively coupled plasmas
- 2.14 Magnetically-enhanced plasmas: ECR, helicon, magnetron, others
- 2.15 Atmospheric and high pressure plasmas: jets and gliding arcs
- 2.16 Atmospheric and high pressure plasmas: dielectric barrier and corona discharges
- 2.17 Atmospheric and high pressure plasmas: catalysis and chemical conversion
- 2.18 Thermal plasmas: arcs, jets, switches, others
- 2.19 Plasmas in liquids
- 2.20 Plasma on or contacting liquids
- 2.21 Plasmas and aerosols
- 2.22 Negative-ion and dust-particle-containing plasmas
- 2.23 Gas phase plasma chemistry
- 2.24 Other plasma science topics

3 Plasma applications

- 3.1 Plasmas for light production: laser media, glows, arcs, flat panels, and novel sources
- 3.2 Plasma etching
- 3.3 Plasma deposition
- 3.4 Plasma ion implantation
- 3.5 Green plasma technologies: environmental and energy applications
- 3.6 Plasma processing for photovoltaic applications
- 3.7 Biological, medical, and agricultural applications of plasmas
- 3.8 Plasma propulsion and aerodynamics
- 3.9 Plasmas for nanotechnologies, flexible electronics, and other emerging applications
- 3.10 Plasma for other materials processing and synthesis

Workshop:

1. Industrial plasma technologies
2. Plasma physics for space propulsion technologies
3. Functional surfaces in plasma elementary and process-applicable reactions
4. Catalytic effects in plasma-liquid interaction

Plenary and Invited Speakers (tentative)

Plenary:

Will Allis Prize Talk



Makabe, Toshiaki (Keio University, Japan)

“40 years with studies on radiofrequency plasma and related transport theory”

The GEC Executive Committee is pleased to recognize Professor Emeritus Makabe as the recipient of the 2022 Will Allis Prize for the Study of Ionized Gases.

Reactive Plasma Award Talk



Hori, Masaru (Nagoya University, Japan)

“Evolution of Reactive Plasma Processes by Radical Control” (tentative)

The International Organizing Committee of ICRP-11 is pleased to recognize Professor Hori as the recipient of the 2022 Reactive Plasma Award.

General Sessions:

Adamovich, Igor	Ohio State University, USA
Agarwal, Sumit	Colorado School of Mines, USA
Akatsuka, Hiroshi	Tokyo Institute of Technology, Japan
Barrachina, Raul	Bariloche Atomic Centre, Argentina
Barret, Steven	Massachusetts Institute of Technology, USA
Bourdon, Anne	Ecole Polytechnique, France
Camata, Renato	University of Alabama at Birmingham, USA
Charles, Christine	The Australian National University, Australia
Chang, Bingdong	Technical University of Denmark, Denmark
Chiang, Wei-Hung	National Taiwan University of Science and Technology, Taiwan
Choe, Wonho	Korea Advanced Institute of Science and Technology, Korea
Colgan, James	Los Alamos National Laboratory, USA
Cvelbar, Uros	Jožef Stefan Institute, Slovenia
Fontes, Christopher	Los Alamos National Laboratory, USA
Gans, Timo	Dublin City University, Ireland

Gherardi, Matteo	University of Bologn, Italy
Gibson, Andrew	Ruhr University Bochum, Germany
Hamdan, Ahmad	Université de Montréal, Canada
Hara, Kentaro	Stanford University, USA
Haruyama, Tetsuya	Kyushu Institute of Technology, Japan
Helmersson, Ulf	Linköping University, Sweden
Hill, Christian	Vienna International Centre, Austria
Hoshino, Masamitsu	Sophia University, Japan
Iqbal, Muzammil	Korea Institute of Machinery and Materials, Korea
Ishikawa, Kenji	Nagoya University, Japan
Kadyrov, Alisher	Curtin University, Australia
Kamataki, Kunihiro	Kyushu University, Japan
Kersten, Holger	Kiel University, Germany
Komuro, Atsushi	The University of Tokyo, Japan
Lacoste, Deanna	King Abdullah University of Science and Technology, Saudi Arabia
Laroussi, Mounir	Old Dominion University, USA
Levko, Dmitry	Esgee Technologies Inc., USA
Likhanskii, Alexandre	Applied Materials, Inc., USA
Lietz, Amanda	North Carolina State University, USA
Lim, Yegeon	Korea Advanced Institute of Science and Technology, Korea
Liu, Dingxin	Xi'an Jiaotong University, China
Maguire, Paul	Ulster University, UK
Mesbah, Ali	University of California, Berkeley, USA
Nagashima, Yasuyuki	Tokyo University of Science, Japan
Namba, Shinichi	Hiroshima University, Japan
Nunomura, Shota	National Institute of Advanced Industrial Science and Technology, Japan
O'Connor, Robert	Dublin City University, Ireland
Oehrlein, Gottlieb	University of Maryland, USA
Ptasinska, Sylwia	University of Notre Dame, USA
Puac, Nevena	Institute of Physics Belgrade, Serbia
Ren, Xueguang	Xi'an Jiaotong University, China
Scheiner, Brett	Los Alamos National Laboratory, USA
Schücker, Lars	Ruhr-University Bochum, Germany
Shigeta, Masaya	Tohoku University, Japan
Shinoda, Kazunori	Hitachi, Ltd., Japan
Smolyakov, Andrei	University of Saskatchewan, Canada
Sun, Jing-Yu	Dalian University of Technology, China
Suzuki, Haruka	Nagoya University, Japan
Tachikawa, Masanori	Yokohama City University, Japan
Takashima, Keisuke	Tohoku University, Japan
Trelles, Juan P.	University of Massachusetts Lowell, USA

Trieschmann, Jan	Brandenburg University of Technology, Germany
Uchida, Giichiro	Meijo University, Japan
Veilleux, Jocelyn	Universite de Sherbrooke, Canada
Zhang, Cheng	Chinese Academy of Sciences, China
Zhang, Yuantao	Shandong University, China
Zheng, Bocong	Fraunhofer USA Center Midwest, Michigan State University, USA

Workshops:

Industrial plasma technologies

Moriya, Tsuyoshi	Tokyo Electron Limited, Japan
Kim, Jaeho	Samsung Electronics, Korea
Lee, Dae Hoon	Korea Institute of Machinery and Materials, Korea
Kenney, Jason	Applied Materials, USA
Ohtake, Hiroto	Hitachi High Technologies America, USA
Tatsumi, Tetsuya	Sony Semiconductor Solutions Corporation, Japan

Plasma physics for space propulsion technologies

Boswell, Rod	Boswell Technologies, Australia
Merino, Mario	Universidad Carlos III de Madrid, Spain
Little, Justin	University of Washington, USA
Fruchtman, Amnon	Holon Institute of Technology, Israel
Mazouffre, Stéphane	CNRS - ICARE laboratory, France
Kawashima, Rei	Shibaura Institute of Technology, Japan
Cho, Shinatora	Japan Aerospace Exploration Agency, Japan

Functional surfaces in plasma elementary and process-applicable reactions

Kurahashi, Mitsunori	National Institute for Material Science, Japan
Nakamura, Hiroaki	National Institute for Fusion Science, Japan
Ibano, Kenzo	Osaka University, Japan
Nozaki, Tomohiro	Tokyo Institute of Technology, Japan
Kim, June Young	Seoul National University, Korea
Stamate, Eugen	Technical University of Denmark, Denmark

Catalytic effects in plasma-liquid interaction

Zhou, Renwu	University of Sydney, Australia
Murakami, Tomoyuki	Seikei University, Japan
Shimizu, Naohiro	Nagoya University, Japan
Bogaerts, Annemie	University of Antwerp, Belgium

Contributed Papers

Call for Contributed Papers

Abstracts:

Those who intend to contribute a paper are requested to submit a GEC abstract through the GEC website (<http://www.apsgec.org/gec2022/abstracts.php>). The due date for receipt of abstracts is **June 10, 4 pm US Central Time (9 pm GMT), 2022**. The length for the text of the abstract is limited to **1300 characters**. The title, author(s), and their institutional affiliation(s) are needed for the abstract submission. It is essential that abstracts state concisely, but informatively, the objectives, methods, principal findings, and significance of the work to be presented. The abstracts will be refereed by the GEC Committee, and the authors will be notified of the acceptance of their papers for presentation in **August, 2022**, along with the assignment to specific oral and poster sessions. Post-deadline papers are NOT acceptable.

Proceedings:

The authors are strongly recommended to submit a paper (up to two-page) for the ICRP proceedings volume (a two-column, camera-ready form) by **June 10, 4 pm US Central Time (9 pm GMT), 2022**, prepared according to instructions those appear in the ICRP webpage (https://www.ecei.tohoku.ac.jp/plasma/ICRP-11/submissions_step2.html#page). The conference proceedings containing invited and contributed papers will be available and are included in the registration fee. Please be noted that, before the ICRP proceedings paper submission, **completion of GEC abstract submission and acquisition of log number of GEC abstract through the GEC abstract submission are required.**

JJAP Special Issue:

Invited speakers

The invited speakers are invited to submit a manuscript for the special issue of Japanese Journal of Applied Physics (JJAP) published by IOP Publishing. JJAP accepts original full papers (regular papers) as well as reviews (progress reviews, recommended). JJAP recognizes speakers in satellite workshops as invited speakers and accepts their manuscripts. All accepted papers in the special issue of JJAP will be freely available to public for one year.

Contributed presenters

The presenters of contributed for oral or poster presentations are invited to submit an original full paper for the special issue of JJAP. All accepted papers in the special issue of JJAP will be freely available to public for one year.

Submission site will be opened at 14 September 2022 (tentative)

Deadline for submissions 31 January 2023

Information of the special issue of JJAP

Authors are requested to read the policy on "Submission of original JJAP papers based on contents already published in conference proceedings, extended abstracts, or the likes" carefully before paper submission.

<https://journals.jsap.jp/wp-content/uploads/policy.pdf>

The link for the template (both for regular paper and progress review):

<https://journals.jsap.jp/wp-content/uploads/template-RP.docx>

Manuscript types in the special issue of JJAP

Progress Reviews: Progress Reviews provide concise, efficient overviews covering the latest progresses in a specific research area of applied physics. It can include or be largely based on the recent results from the author(s). Manuscripts should be written as concisely as possible although no limitation on length is specified. Abstract should be no more than 150 words.

Regular Papers: A Regular Paper is an original paper with comprehensive, detailed descriptions of the research work, presenting a fully developed discussion on the results obtained in relevant fields of applied physics. It must provide sufficient and self-contained information to ensure the repeatability of experiments and analyses by readers. There is no length limit. The expected number of references is approximately more than 30. No upper or lower limit is specified.



Social Events

Welcome Reception:

Monday, October 3, 2022.

Banquet:

Thursday, October 6, 2022.

Closing Ceremony:

Friday, October 7, 2022.

ICRP Committees

International Organizing Committee

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H. Tanaka	Nagoya University
Y. Tanaka	Kanazawa University
K. Tomita	Hokkaido University

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K. Takenaka	Osaka University
A. Ogino	Shizuoka University
H. Kurita	Toyohashi University of Technology
S. Uchida	Tokyo Metropolitan University
N. Kuboi	Sony Corporation

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A. Ando	Tohoku University
T. Sato	Tohoku University
N. Ohnishi	Tohoku University
M. Shigeta	Tohoku University
T. Kato	Tohoku University
K. Takahashi	Tohoku University
T. Okada	Tohoku University
H. Takana	Tohoku University
K. Takashima	Tohoku University
S. Sasaki	Tohoku University
K. Ishikawa	Nagoya University
H. Komen	Osaka University

GEC Committees

GEC Executive Committee Members

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S. Rauf (Chair elect)	Applied Materials Inc.
G. Xu (Past secretary)	University of Alabama in Huntsville
T. Kaneko (Secretary)	Tohoku University
S. Baalrud (Secretary elect)	University of Michigan
A. Derzsi (Treasurer)	Wigner Research Centre for Physics, Hungary
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M. Koepke	West Virginia University
M. Kushner	University of Michigan
S. Quintanilla	University of North Texas
S. Reuter	Ecole Polytechnique de Montreal
T. Shimizu	National Institute of Advanced Industrial Science and Technology

Hotel Accommodation

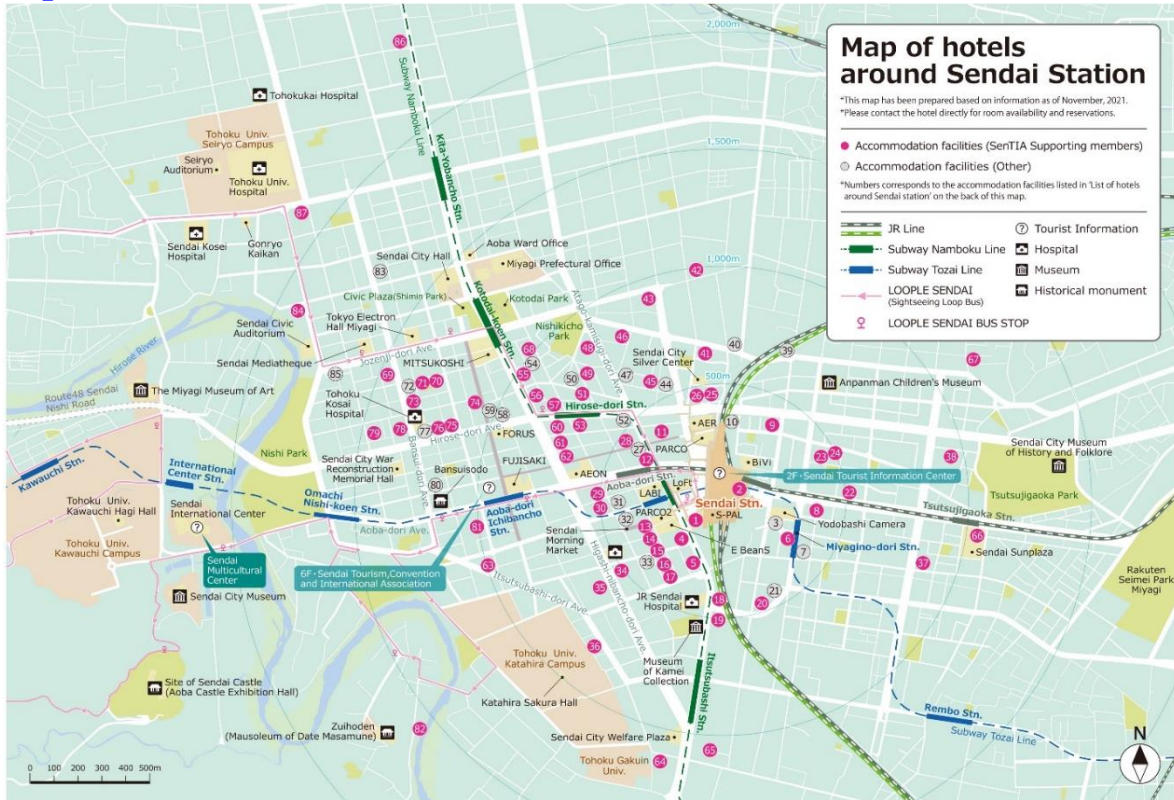
There are many hotels in Sendai. We recommend that you make your own reservations at the hotel reservation websites listed below.

[Expedia](#)

[Booking.com](#)

[Trivago](#)

Map of Hotels:



List of Hotels :

[Accommodation facilities (SenTIA Supporting members)]

● Within 500 meters radius from Sendai Stn.

No	Name	TEL	Rooms
1	HOTEL METROPOLITAN SENDAI	81-22-268-2525	295
2	HOTEL METROPOLITAN SENDAI EAST	81-22-302-3373	282
4	Hotel Monterey Sendai	81-22-265-7110	206
5	WASHINGTON HOTEL SENDAI	81-22-745-2222	223
6	HOTEL VISTA SENDAI	81-22-385-6222	238
8	SENDAI GARDEN PALACE	81-22-299-6211	66
9	Comfort Hotel Sendai East	81-22-792-8711	202
11	HOTEL Green Pacific	81-22-221-8888	92
12	Richmond Hotel Premier Sendai Ekimae	81-22-716-2855	183
13	HOTEL Green Well	81-22-216-6155	47
14	HOTEL UNISITE SENDAI	81-22-716-0123	144
15	HOTEL CENTRAL SENDAI	81-22-711-4111	97
16	SENDAI BUSINESS HOTEL STATION FRONT	81-22-262-3211	250
17	HOTEL Green Mark	81-22-224-1050	140
18	Toyoko Inn Sendai-eki Nishi-guchi Chuo	81-22-726-1045	286
19	APA Villa Hotel Sendai-Eki Itsutsubashi	05704023-111	610
20	ANA Holiday Inn SENDAI	81-22-256-5111	165
22	Hotel Grand Bach Sendai	81-22-296-0660	151
23	Toyoko Inn Sendai Higashi-guchi No.1	81-22-256-1045	208
24	Toyoko Inn Sendai Higashi-guchi No.2	81-22-298-1045	120
25	HOTEL JAL CITY SENDAI	81-22-711-2580	238
26	Hotel Monte Hermana SENDAI	81-22-721-7501	275
28	HOTEL Premium Green PLUS	81-22-212-1255	117
29	HOTEL KEIHAN SENDAI	81-22-263-0321	201
30	ALMONT HOTEL SENDAI	81-22-212-6551	141
34	Sendai Kokusai Hotel	81-22-268-1111	234

● Within 1,000 meters radius from Sendai Stn.

No	Name	TEL	Rooms
35	The Westin Sendai	81-22-722-1234	292
36	Alsaki Ryokan (Inn)	81-22-264-0700	15
37	HOTEL MIELPARQUE SENDAI	81-22-792-8111	122
38	Oka no Hotel	81-22-256-7311	35
41	Richmond Hotel Sendai	81-22-722-0055	344
42	HOTEL SHIRAHAGI	81-22-265-3411	28
43	SENDAI ROYAL MAYFLOWER	81-22-262-5411	182
45	Toyoko Inn Sendai Nishi-guchi Hirose-dori	81-22-721-1045	210
46	Daiichi Inn Park	81-22-213-0089	85
48	HOTEL HOKKE CLUB SENDAI	81-22-224-3121	151
49	HOTEL Green Selec	81-22-217-3117	77
51	R&B Hotel Sendai Hirose-dori Ekimae	81-22-726-1919	202
53	dormy inn EXPRESS Sendai Hirose-dori	81-22-715-7077	120
55	LIBRARY HOTEL HIGASHI-NIBANCHO	81-22-221-7666	230
56	Mitsui Garden Hotel Sendai	81-22-214-1131	224
57	KOYO GRAND HOTEL	81-22-267-5111	149
60	Super Hotel Sendai / Hirose-dori	81-22-224-9000	173
61	HOTEL Premium Green Hills	81-22-722-1501	118
62	HOTEL CROWN HILLS SENDAI AOBADORI	81-22-262-1355	154
63	Hotel Bel Air Sendai	81-22-217-8511	125

● Within 1,500 meters radius from Sendai Stn.

No	Name	TEL	Rooms
64	MORISHIGE RYOKAN	81-22-222-5373	15
65	Hostel KIKO	81-22-281-9788	40
66	SENDAI SUNPLAZA	81-22-257-3333	74
67	HOTEL Green Palace	81-22-256-2691	88
68	Business Hotel TAIYO	81-22-221-1955	78
69	HOTEL Green Park	81-22-265-6171	72
70	HOTEL Premium Green SOVEREIGN	81-22-227-2322	92
71	Capsule Hotel Leaves	81-22-261-8020	120
73	SAUNA & CAPSULE CURE KOKUBUNCHO	81-22-713-8526	186
74	Smile Hotel Sendai Kokubuncho	81-22-261-7711	202
75	Hotel Grand Terrace Sendai Kokubun-cho	81-22-262-7755	294
76	HOTEL Green With	81-22-261-3737	78
78	MORI NO HOTEL SENDAI	81-22-713-5888	77
79	HOTEL Green Arbor	81-22-213-8990	64
81	HOTEL PEARL CITY SENDAI	81-22-262-8711	166

● Within 2,000 meters radius from Sendai Stn.

No	Name	TEL	Rooms
82	Ryokan Otamaya	81-22-222-7892	20
84	HOTEL Green Line	81-22-217-8311	83

● Within 2,500 meters radius from Sendai Stn.

No	Name	TEL	Rooms
86	HOTEL Green City	81-22-219-2691	80
87	BANSUITEI IKOISO	81-22-222-7885	14

Printed version of map and list of hotels:

https://www.sentia-sendai.jp/conventionnavi-en/wp-content/themes/theme_convnavi_child/pdf/w2022-sendai_hotels_list-en_202202.pdf

*Please note the above map and list of hotels are based on information as of Nov.2021.

Visas

Firstly, please complete the advanced registration. Check the "Guide to Japanese VISA" through the URL below.

Ministry of Foreign Affairs of Japan (http://www.mofa.go.jp/j_info/visit/visa/index.html)

Please fill in the necessary documents for your VISA application and send by e-mail to the ICRP-11 Congress Secretariat

(E-mail : icrp11@senkyo.co.jp).

We will complete the documents and send back to you by mail.

Further Information

Details of the scientific program and daily schedule will be given in the third announcement, which will be posted on ICRP website around September. All questions for further information regarding this conference should be directed to the Conference Chair.

Also available is the ICRP-11/GEC2022 URL:

<https://www.ecei.tohoku.ac.jp/plasma/ICRP-11/index.html>

If you know of individuals who may have a paper to contribute and have not received this *Second Announcement and Call for Papers*, please bring it to their attention.

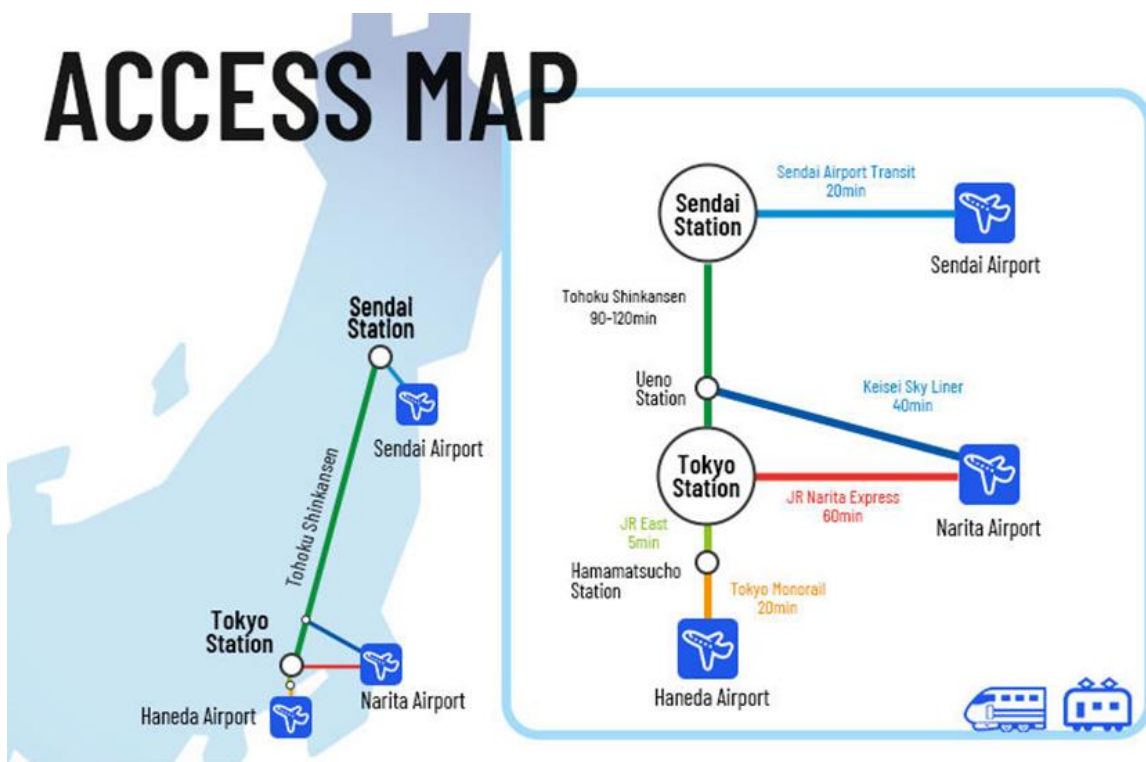
Calendar of Events

GEC abstract deadline	June 10, 2022
Paper deadline for a ICPR proceedings (up to two pages, a two-column, camera-ready form)	June 10, 2022
Deadline for student travel support	June 10, 2022
Registration starts	July, 2022
Notification of acceptance	August 2022
Final announcement/program	September 2022
ICRP-11 / GEC 2022	October 3-7, 2022
Papers deadline for JJAP special issue	January, 2023

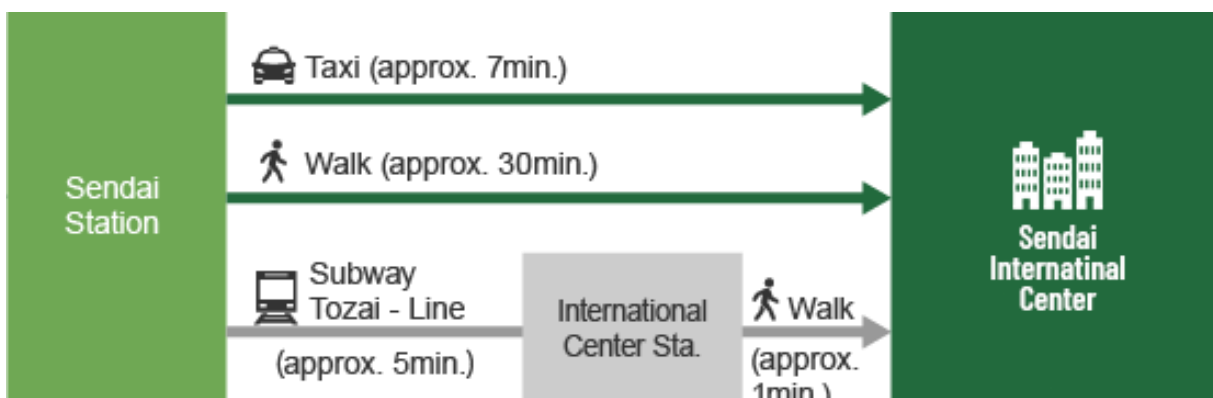
Travel Information

Tokyo has two international airports, Haneda and Narita, with many international flights, making it easy to get to Japan from anywhere in the world. There are two daily direct flights from Narita airport to Sendai. It takes 30 minutes by train from Sendai Airport to downtown Sendai. On the other hand, if you are traveling by train from Narita or Haneda airports, you can take the Shinkansen (bullet train) from the respective airports to Sendai via Tokyo Station. It takes 90 minutes from Tokyo Station to Sendai Station by Shinkansen.

Access 1: form Tokyo Airports (Narita/Haneda) to Sendai Station



Access 2: form Sendai Station to the venue



ICRP-11 Office

Congress Secretariat

E-mail : icrp-11@grp.tohoku.ac.jp

URL : <https://www.ecei.tohoku.ac.jp/plasma/ICRP-11/>